

Electronic Patent Application Fee Transmittal

Application Number:	10611334			
Filing Date:	30-Jun-2003			
Title of Invention:	MEMS packaging using a non-silicon substrate for encapsulation and interconnection			
First Named Inventor/Applicant Name:	John Heck			
Filer:	Kevin Reiff/cathy dikes			
Attorney Docket Number:	42P16325			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Independent claims in excess of 3	1201	2	200	400
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				400